

DIE SPECIFICATION

60V 300mA MONOLITHIC DIODE ARRAY

FEATURES:

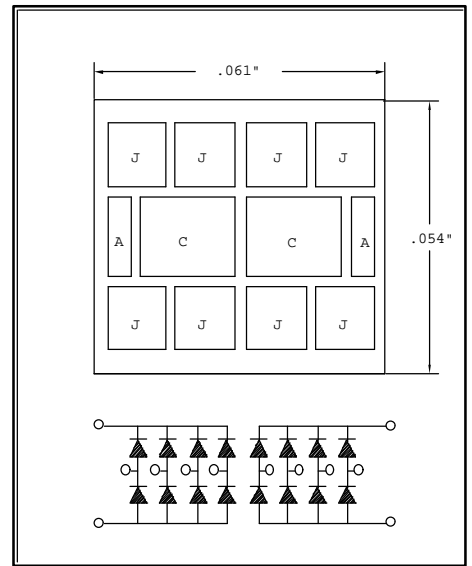
- TWO EIGHT DIODE CORE DRIVER
- $t_{tr} < 20$ ns
- RUGGED AIR-ISOLATED CONSTRUCTION
- LOW REVERSE LEAKAGE CURRENT

Absolute Maximum Ratings:

| Symbol | Parameter | Limit | Unit |
|--------|--------------------------------------|-------------|------|
| VBR(R) | *1 *2 Reverse Breakdown Voltage | 60 | Vdc |
| IO | *1 Continuous Forward Current | 300 | mAdc |
| IFSM | *1 Peak Surge Current (tp= 1/120 s) | 500 | mAdc |
| Top | Operating Junction Temperature Range | -65 to +150 | °C |
| Tstg | Storage Temperature Range | -65 to +200 | °C |

NOTE 1: Each Diode

NOTE 2: Pulsed: PW = 100ms max.; duty cycle \leq 20%



Electrical Characteristics (Per Diode) @ 25°C unless otherwise specified

| Symbol | Parameter | Conditions | Min | Max | Unit |
|--------|--------------------------|---|-----|-----|------|
| BV1 | Breakdown Voltage | IR = 10uAdc | 60 | | |
| Vf1 | Forward Voltage | IF = 100mAdc *1 | | 1 | Vdc |
| Vf2 | Forward Voltage | IF = 500mAdc *1 | | 1.5 | Vdc |
| IR1 | Reverse Current | VR = 40 Vdc | | 0.1 | uAdc |
| Ct | Capacitance (pin to pin) | VR = 0 Vdc ; f = 1 MHz | | 8.0 | pF |
| tfr | Forward Recovery Time | IF = 500mAdc | | 40 | ns |
| trr | Reverse Recovery Time | IF = IR = 200mAdc, irr = 20 mAdc, RL = 100 ohms | | 20 | ns |

NOTE 1: Pulsed: PW = 300us +/- 50us, duty cycle \leq 2%, 90us after leading edge

Packaging Options:

| | |
|--|--------------------------|
| W: Wafer (100% probed) | U: Wafer (sample probed) |
| D: Chip (Waffle Pack) | B: Chip (Vial) |
| V: Chip (Waffle Pack, 100% visually inspected) | X: Other |

Processing Options:

| | |
|-----------|--|
| Standard: | Capable of JANTXV application (No Suffix) |
| Suffix C: | Commercial |
| Suffix S: | Capable of S-Level equivalent applications |

Metallization Options:

| | |
|------------------|---------------------------|
| Standard: Al Top | / Au Backside (No Dash #) |
|------------------|---------------------------|

ORDERING INFORMATION

PART #: 28M0__-__

First Suffix Letter: Packaging Option
Second Suffix Letter: Processing Option
Dash #: Metallization Option

Sertech reserves the right to make changes to any product design, specification or other information at any time without prior notice.